L Number	Hits	Search Text	DB	Time stamp
-	1	("6331736").PN.	USPAT	2004/01/26 11:58
-	0	("8222840").PN.	JPO; DERWENT	2004/01/26 11:59
-	2	"08222840"	JPO; DERWENT	2004/01/26 12:20
-	1	"55050659"	JPO; DERWENT	2004/01/26 12:38
-	1	("6054198").PN.	USPAT	2004/01/26 13:09
-	19574	(chip or die) and ((adhesive or underfill or encapsul$4) with (hole$1 or space$1 or gap$1 or air or gas))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/26 13:10
-	9447	((chip or die) and ((adhesive or underfill or encapsul$4) with (hole$1 or space$1 or gap$1 or air or gas))) and (@ad<19970904)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/26 13:11
-	3015	(((chip or die) and ((adhesive or underfill or encapsul$4) with (hole$1 or space$1 or gap$1 or air or gas))) and (@ad<19970904)) and (semiconductor or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/26 13:12
-	2250	((((chip or die) and ((adhesive or underfill or encapsul$4) with (hole$1 or space$1 or gap$1 or air or gas))) and (@ad<19970904)) and (semiconductor or IC)) and (substrate or board or pwb or pcb)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/26 13:12
-	1226	(((((chip or die) and ((adhesive or underfill or encapsul$4) with (hole$1 or space$1 or gap$1 or air or gas))) and (@ad<19970904)) and (semiconductor or IC)) and (substrate or board or pwb or pcb)) and 257/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/26 13:13